ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and	<b>nposition De</b> 5. IPC, Bannockt Pan-American co	<b>claration</b> ourn, Illinois. A opyright conve	All rights reserved untions.	nder both	This docume level parts, th	ent is a declaration entities of the declaration entities	on of the substan	ces within the man ower level materia	nufacturer listed ls for which the	d item. Note: i e manufacturer	f the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ   http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information			
upplier Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2023-06-08			
Contact Name Title - Contact			ct	Pł		Phone - Contact*			Emai	Email - Contact*			
Product-Env-Stewards Pr			Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - 1			itle - Representative			Phone - Representative*			Emai	Email - Representative*			
Product-Env-Stewards P			Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	Version	Manufacturing	Site	Weight*	UOM	Unit Type	
	LM2575	LM2575TV-ADJG ANA ADJV		A PWR SW REG		2023-06-08		MY1		1960.42	mg	Each	
Ianufacturing Proccess Inform	nation												
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature Max Time a		at Peak Tempe	ak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30	sec	seconds 3				
omments													
or more information regarding mater	rial composition	please refer to	) page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in the sparaph. If the Company and the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and/conditions of Sale applicable to such part, shall apply.										
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter [F] Optionally enter the positive (+) and				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.83	mg	А	Lead (Pb)	7439-92-1	7a	78.6885	mg
			Supplier	Tin (Sn)	7440-31-5		4.1415	mg
Lead Frame	1297.64	mg	Supplier	Copper (Cu)	7440-50-8		1297.64	mg
Mold Compound-Black	543.9	mg		Epoxy resin	proprietary data		38.073	mg
			Supplier	Phenolic Resin	Proprietary Data		38.073	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		81.585	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		383.4495	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg